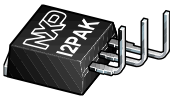


SOT226B

Plastic single-ended package (I2PAK); low-profile 3-lead TO-262

13 July 2016

Package information

1. Package summary

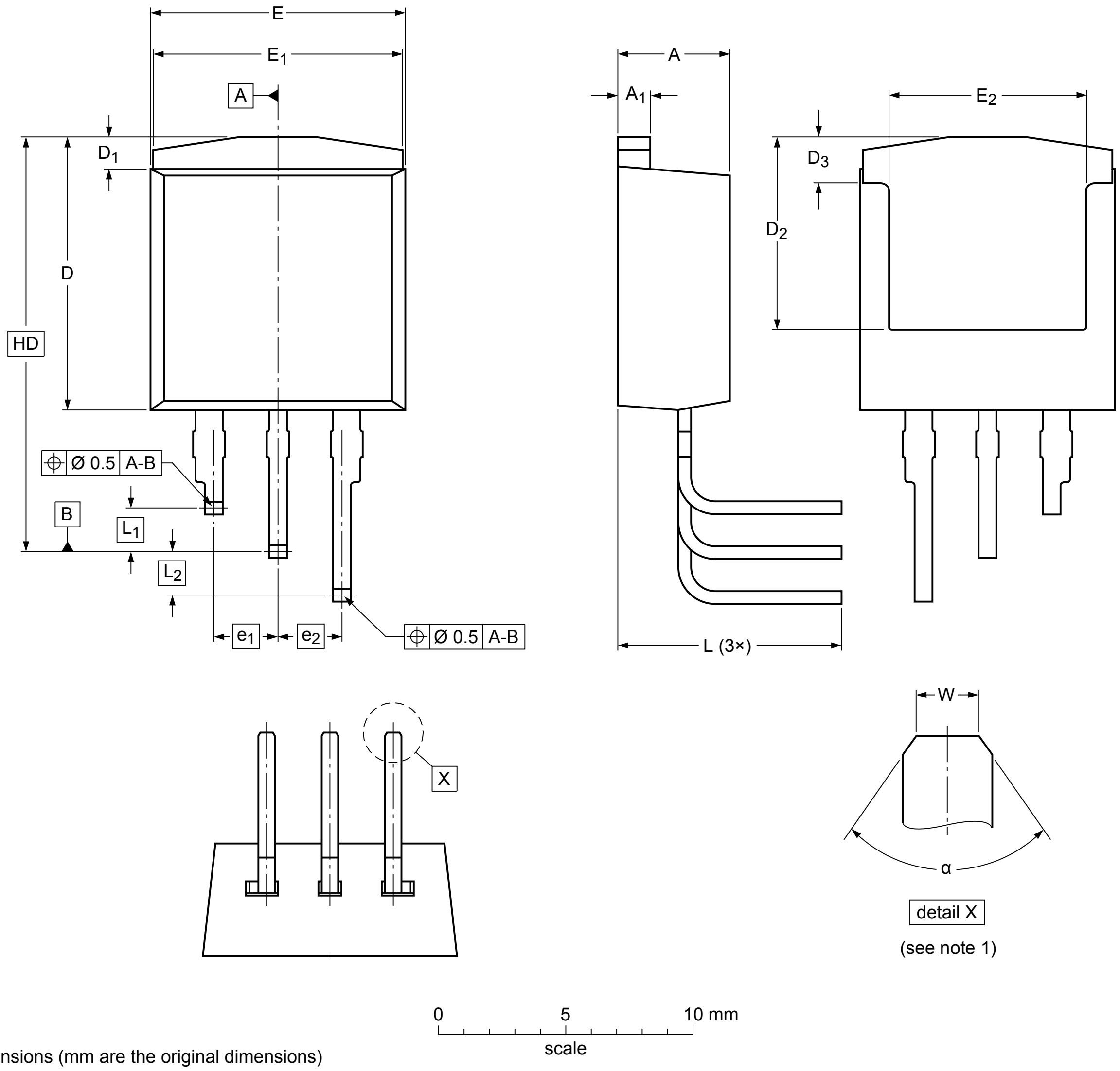
Dimensions (mm)	11 x 10 x 4.5
Terminal position code	S (single)
Package type descriptive code	I2PAK
Package outline version code	SOT226B
Manufacturer package code	SOT226
Package type industry code	I2PAK
Package outline version description	Plastic single-ended package (I2PAK); low-profile 3-lead TO-262
Package style descriptive code	SIP (single in-line package)
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	T (through-hole mount)
Generic mounting and soldering information	SC18_2004_CHAPTER_4_3
Major version date	24-10-2012
Minor version date	24-10-2012
Security status	COMPANY PUBLIC
Modified date	29-10-2012
Issue date	8-6-2016
Web publication date	28-11-2012
Initial web publication date	24-10-2012
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A_2	package height		-	-	-	-	
A	seated height		4.1	-	4.3	4.5	mm
D	package length		-	-	-	11	mm
E	package width		9.7	-	-	10.3	mm
e	nominal pitch		-	-	2.54	-	mm
n_2	actual quantity of termination		-	-	3	-	

2. Package outline

Plastic single-ended package (I2PAK); low-profile 3-lead TO-262 **SOT226B**



Dimensions (mm are the original dimensions)

Unit[1]		A	A_1	D	D_1	D_2	D_3	E	E_1	E_2	e_1	e_2	L	L_1	L_2	HD	W	α
mm	max	4.5	1.40	11.0	1.6			10.3	10.2		2.79	2.79	9.32	1.97	1.97	16.78	0.75	75°
	nom																	
	min	4.1	1.27		1.2	7.0	1.2	9.7	9.6	7.2	2.29	2.29	8.32	1.47	1.47	16.28	0.25	65°

Note

1. Chamfer tooling to produce chamfer features based on unformed leads (non-symmetrical chamfers permitted).
Third leg chamfer angle 70° (per unformed device specification).

sot226b_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT226B						~~16-06-06~~ 16-06-08

Fig. 1. Package outline I2PAK (SOT226B)

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4. Contents

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